TEXAS INSTRUMENTS **12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

PCN# 20131209002

Qualification of RFAB and JCAP as additional Fab site and Assembly/Test site options for select devices in the LBC8LV process

Change Notification / Sample Request

Date: 12/27/2013

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20131209002
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
DRV2605YZFT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20131209002	**PCN Date:**	12/27/2013

Title:	Qualification of RFAB and JCAP as additional Fab site and Assembly/Test site options for select devices in the LBC8LV Fab process.

Customer Contact:	PCN Manager	**Phone:**	+1(214)480-6037	**Dept:**	Quality Services

***Proposed 1st Ship Date:**	03/27/2014	**Estimated Sample Availability:**	Date Provided at Sample request

Change Type:

☒	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☒	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☒	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

This change notification is to announce the addition of RFAB and JCAP as additional Fab site and Assembly/Test site options for select devices in the LBC8 Fab Process. There are no changes to the Bill of Materials as a result of this change. Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.

Group 1 (Fab Site):

Current Site/Process/Wafer Diameter	Additional Site/Process/Wafer Diameter
UMC-F8E/LBC8LV Process/200mm	RFAB/LBC8LV Process/300mm

Group 2 (Assembly Site):

TI Clark - Philippines	Assembly Site Origin (22L)	ASO: QAB
JCAP	Assembly Site Origin (22L)	ASO: JCP

The LBC8 process was qualified at RFAB on 2/14/2013. The WCSP package was qualified at JCAP on 2/19/2013. Qualification results are shown below.

Reason for Change:

Continuity of supply.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Fab Site

Current Chip Site	Chip Site Code (20L)	Chip Country Code (21 L)
UMC-F8E	CSO: U8E	TWN
New Chip Site	Chip Site Code (20L)	Chip Country Code (21 L)
RFAB	CSO: RFB	USA

Assembly Site

Current Assembly Site		
Clark-AT	Assembly Site Origin (22L)	ASO: QAB
New Assembly Site		
JCAP-AT	Assembly Site Origin (22L)	ASO: JCP

The symbolization will remain the same.
ASSEMBLY SITE CODES: TI CLARK =I, JCAP = P

Sample Product Shipping Label (not actual product label)

TEXAS INSTRUMENTS
MADE IN: Malaysia
2DC: 2Q:
MSL 2 /260C/1 YEAR | SEAL DT
MSL 1 /235C/UNLIM | 03/29/04
OPT:
ITEM: 39
LBL: 5A (L)TO:1750

G4

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected Group 1 (Fab Site):

DRV2604YZFR	DRV2604YZFT	DRV2605YZFR	DRV2605YZFT

Product Affected Group 2 (Assembly and Test Site):

DRV2604YZFR	DRV2604YZFT	DRV2605YZFR	DRV2605YZFT

Qualification Data Group 1: Approved 2/14/2013

This qualification has been developed for the validation of this change. The qualification data will validate that the proposed change meets the applicable released technical specifications.

Qualification Device 1: SH8350BCA0PAPG4 (MSL LEVEL3-260C)

Wafer Fab Site:	RFAB	Wafer Fab Process:	LBC8
Wafer Diameter:	300mm		

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size / Fail		
		Lot#1	Lot#2	Lot#3
Life Test	125C (1000 hours)	77/0	76/0	71/0
Electrical Characterization	Per datasheet specification	Pass	-	-
**Biased HAST	130C/85%RH (96 hours)	77/0	77/0	77/0
**Autoclave	121C (96 hours)	77/0	77/0	77/0
**Temp Cycle	-65/150C (500 cycles)	77/0	77/0	77/0
**High Temp Storage Bake	170C (420 hours)	77/0	77/0	77/0
ESD CDM	Per datasheet	5/0	5/0	5/0
ESD HBM	Per datasheet	5/0	5/0	5/0
Latch-up	Per JESD78	6/0	6/0	6/0

**Preconditioning: Level 3-260C

Qualification Data Group 2: Approved 2/19/2013

This qualification has been developed for the validation of this change. The qualification data will validate that the proposed change meets the applicable released technical specifications.

Qualification Device 1: CD3230A0YFF (MSL LEVEL1-260C)

Assembly Site:	JCAP	Bump Composition:	SnAgCu
# Pins-Designator, Family:	130-YFF, WCSP	Bump Diameter:	0.25mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size / Fail		
		Lot#1	Lot#2	Lot#3
**Unbiased HAST	130C/85%RH (96 hours)	85/0	82/0	78/0
**High Temp Storage Bake	170C (420 hours)	84/0	80/0	78/0
**Biased HAST	130C/85%RH (96 hours)	85/0	-	-
Life Test	125C (1000 hours)	80/0	-	-
**Temp Cycle	-55/125C (1000 cycles)	85/0	85/0	78/0

**Preconditioning: Level 1-260C

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	**E-Mail**
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com